

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	5424753	(semiconductor chip die dice electronic ic (integrated adj circuit) flipchip (flip adj chip))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 10:54
L2	963097	1 with (substrate carrier board pcb ((wiring printed circuit circuitry) adj4 board))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 10:55
L3	27357	(underfill ((resin insulat\$4) with (fill\$4 gap))) same 2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 10:58
L4	90255	(underfill resin ((resin insulat\$4) with (fill\$4 spac\$3 gap))) same 2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 11:01
L5	63143	(underfill resin ((resin insulat\$4) with (fill\$4 spac\$3 gap))) with 2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 11:02
L6	21613	(thermal expansion coefficient) and 5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 11:10
L7	16121	(stud stiffener sink spreader metal post) and 6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 11:04
L8	6953	(flipchip (flip adj chip) ball bump) and 7	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 11:05

## EAST Search History

L9	6861	8 and (other plurality multiple first second top bottom upper lower)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 11:06
L10	6530	(gap\$4 fill\$4 opening void spac\$4) and 9	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 11:08
L11	2830	(underneath underfill beneath) and 9	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 11:09
L12	1920	(thermal with (expansion coefficient)) and 11	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 11:10